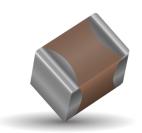
General Specifications





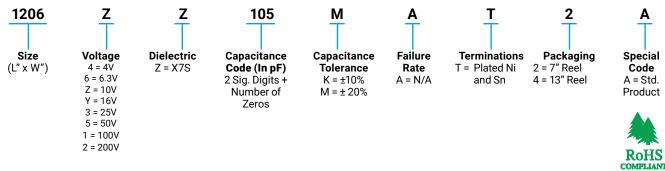
GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitance s within $\pm 22\%$ from -55° C to $\pm 125^{\circ}$ C. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

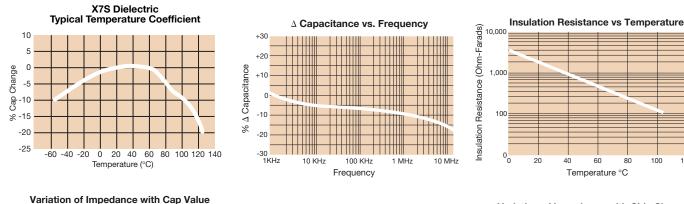
X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

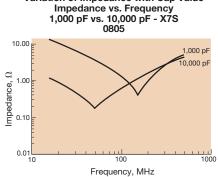
PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)

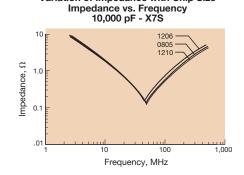


NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

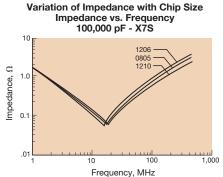
TYPICAL ELECTRICAL CHARACTERISTICS







Variation of Impedance with Chip Size



X7S Dielectric

Specifications and Test Methods



Parame	ter/Test	X7S Specification Limits	Measuring Conditions				
Operating Tem	perature Range	-55°C to +125°C	Temperature C	ycle Chamber			
Capac	itance	Within specified tolerance					
Dissipation Factor		≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz				
Insulation	Resistance	100,000ΜΩ or 1000ΜΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo				
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50	and discharge current			
	Appearance	No defects	Deflection: 2mm Test Time: 30 seconds 1mm/sec				
Resistance to	Capacitance Variation	≤ ±12%					
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	V V				
	Insulation Resistance	≥ Initial Value x 0.3	90 r	mm			
Solde	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic solder at 230 ± 5°C for 5.0 ± 0.5 seconds				
	Appearance	No defects, <25% leaching of either end terminal					
	Capacitance Variation	≤ ±7.5%					
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260° C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.				
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	nours perore measuring electrical properties.			
	Dielectric Strength	Meets Initial Values (As Above)					
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes			
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes			
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes			
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes			
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro				
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C				
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hours (+48, -0) Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring.				
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)					
	Dielectric Strength	Meets Initial Values (As Above)					
	Appearance	No visual defects					
	Capacitance Variation	≤ ±12.5%	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.				
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)					
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)					
	Dielectric Strength	Meets Initial Values (As Above)					

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X7S Dielectric

Capacitance Range



PREFERRED SIZES ARE SHADED

SIZE		0402	0603	0805	1206			1210	
Soldering		Reflow/Wave	Reflow/Wave	Reflow/Wave	Reflow/Wave		ave	Reflow Only	
Packa		All Paper	All Paper	Paper/Embossed	Pape	Paper/Embossed		Paper/Embossed	
mm		1.00 ± 0.10	1.60 ± 0.15	2.01 ± 0.20	3.	20 ± 0.:	20	3.20 ± 0.20	
(L) Length	(in.)	(0.040 ± 0.004)	(0.063 ± 0.006)	(0.079 ± 0.008)	(0.126 ± 0.008)		(800	(0.126 ± 0.008)	
W) Width	mm	0.50 ± 0.10	0.81 ± 0.15	1.25 ± 0.20	1.	60 ± 0.:	20	2.50 ± 0.20	
w) width	(in.)	(0.020 ± 0.004)	(0.032 ± 0.006)	(0.049 ± 0.008)	(0.063 ± 0.008)		(800	(0.098 ± 0.008)	
(t)	mm	0.25 ± 0.15	0.35 ± 0.15	0.50 ± 0.25	0.50 ± 0.25		25	0.50 ± 0.25	
Terminal	(in.)	(0.010 ± 0.006)	(0.014 ± 0.006)	(0.020 ± 0.010)	(0.0	(0.020 ± 0.010)		(0.020 ± 0.010)	
	WVDC	6.3	6.3	4	10	50	100	6.3	
Сар	100								
(pF)	150								
" /	220					I	_		
	330							\sim	
	470				~				
	680					(-	_	\	
	1000)		
	1500								
İ	2200						4	-	
	3300						[_	
İ	4700					1	l		
	6800					İ			
Сар	0.010								
(µF)	0.015								
(F-)	0.022								
	0.033	С							
	0.047	C							
	0.068	C							
	0.10	C							
	0.15	O							
	0.13								
	0.22		G		-		<u> </u>		
	0.47		G						
	0.47		G						
	1.0		G						
	1.5		· ·	N					
	2.2			l N					
	3.3			N			 		
	4.7			N N	Q		0*		
	10			",	٧ .		٧		
	22							Z	
	47						1	_	
	100								
	WVDC	6.3	6.3	4	10	50	100	6.3	
SIZE		0402	0603	0805	10	1206		1210	
	JIZE	0702	0003	0000		1200		1210	

[Letter	Α	С	E	G	J	K	М	N	Р	Q	X	Υ	Z
	Max.	0.33	0.56	0.71	0.90	0.94	1.02	1.27	1.40	1.52	1.90	2.29	2.54	2.79
1	Thickness	(0.013)	(0.022)	(0.028)	(0.035)	(0.037)	(0.040)	(0.050)	(0.055)	(0.060)	(0.075)	(0.090)	(0.100)	(0.110)
		PAPER				EMBOSSED								

^{*}Contact Factory for Specifications

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